

N-Channel 60-V (D-S), 175 °C MOSFET

PRODUCT SUMMARY			
V _{(BR)DSS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)	
60	0.011	70	

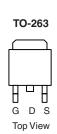
FEATURES

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- · Low Thermal Resistance Package

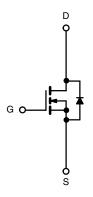


APPLICATIONS

Industrial



Ordering Information: SUM70N06-11 SUM70N06-11-E3 (Lead (Pb)-free)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _C = 25 °C, unless oth	erwise noted		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V _{GS}	± 20	V
Continuous Drain Current (T _J = 175 °C)	T _C = 25 °C		70	
	T _C = 100 °C		49	
Pulsed Drain Current		I _{DM}	160	Α
Avalanche Current		I _{AR}	35	
Repetitive Avalanche Energy ^a	L = 0.1 mH	E _{AR}	61	mJ
Power Dissipation	T _C = 25 °C		120 ^b	147
	T _A = 25 °C°	P _D	3.75	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	40	°C/W	
Junction-to-Case		R _{thJC}	1.25	C/ VV	

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).

For SPICE model information via the Worldwide Web: http://www.vishay.com/www/product/spice.htm.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

SUM70N06-11

Vishay Siliconix



SPECIFICATIONS $T_J = 25$ °	C, unless of	therwise noted				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{DS} = 250 \mu A$	2.0	3.0	4.0	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current		V _{DS} = 48 V, V _{GS} = 0 V			1	μΑ
	I _{DSS}	V _{DS} = 48 V, V _{GS} = 0 V, T _J = 125 °C			50	
		V _{DS} = 48 V, V _{GS} = 0 V, T _J = 175 °C			250	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	70			Α
Drain-Source On-State Resistance ^a		V _{GS} = 10 V, I _D = 30 A		0.0085	0.011	Ω
	r _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}, T_J = 125 ^{\circ}\text{C}$			0.019	
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C			0.025	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 30 \text{ A}$	25	50		S
Dynamic ^b	•			•		
Input Capacitance	C _{iss}			2500		pF
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		400		
Reverse Transfer Capacitance	C _{rss}			165		
Total Gate Charge ^c	Qg	V _{DS} = 30 V, V _{GS} = 10 V, I _D = 70 A		40	60	nC
Gate-Source Charge ^c	Q_{gs}			13		
Gate-Drain Charge ^c	Q_{gd}			12		
Turn-On Delay Time ^c	t _{d(on)}			15	25	
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V, } R_L = 0.43 \ \Omega$ $I_D \cong 70 \text{ A, } V_{GEN} = 10 \text{ V, } R_G = 2.5 \ \Omega$		11	20	ns
Turn-Off Delay Time ^c	t _{d(off)}			30	50	
Fall Time ^c	t _f			7	15	
Source-Drain Diode Ratings and Cha	aracteristics 7	_C = 25 °C ^b		•		
Continuous Current	I _S				70	A
Pulsed Current	I _{SM}				160	
Forward Voltage ^a	V_{SD}	I _F = 50 A, V _{GS} = 0 V		1.0	1.5	V
Reverse Recovery Time	t _{rr}			40	80	ns
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 70 A, di/dt = 100 A/μs		1.7	3.5	Α
Reverse Recovery Charge	Q _{rr}			0.034	0.14	μC

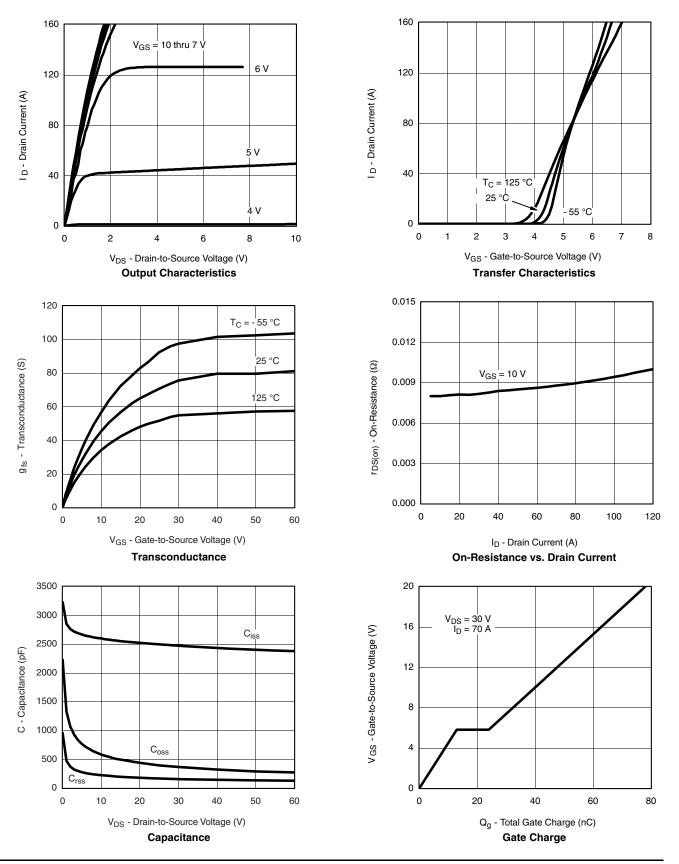
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

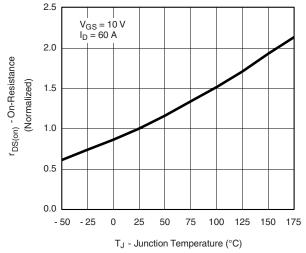


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

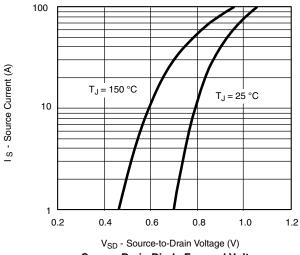


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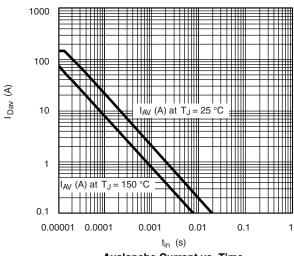
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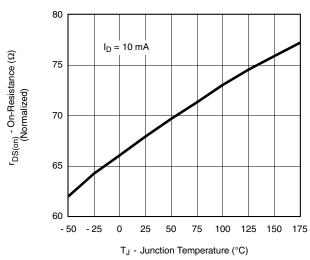
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



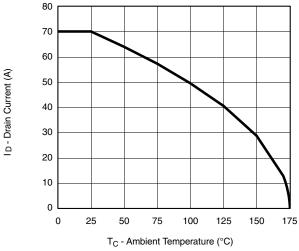
Avalanche Current vs. Time

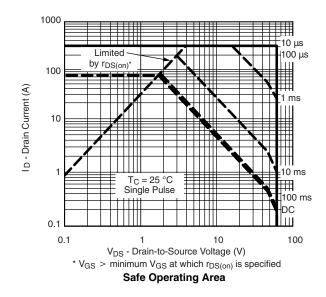


On-Resistance vs. Junction Temperature

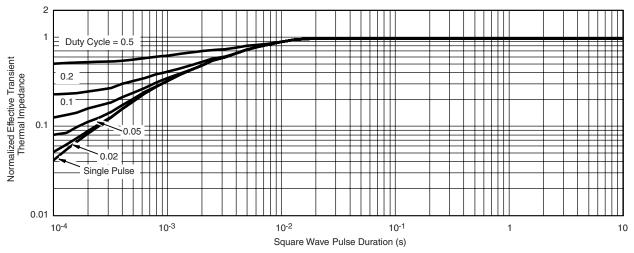


THERMAL RATINGS





Maximum Drain Current vs. Case Temperature



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72008.



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